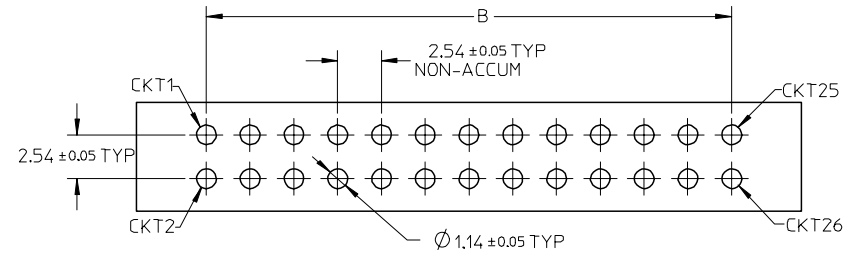
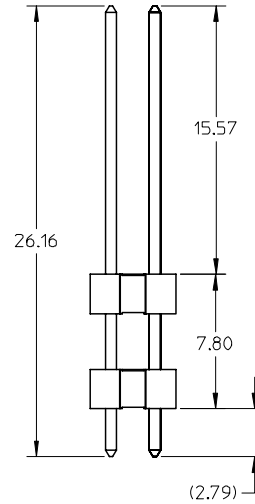
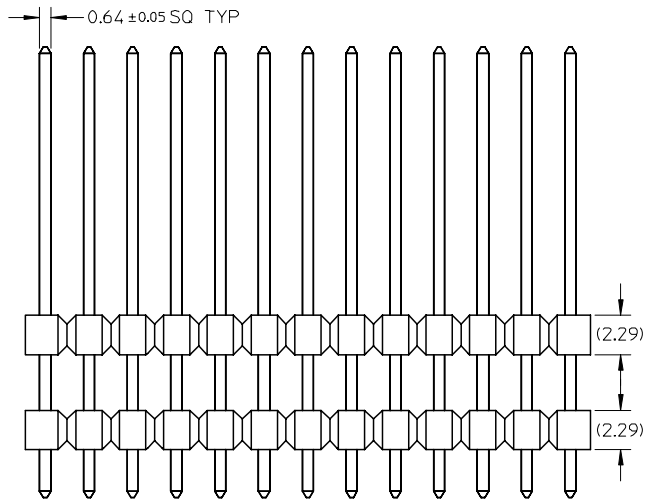
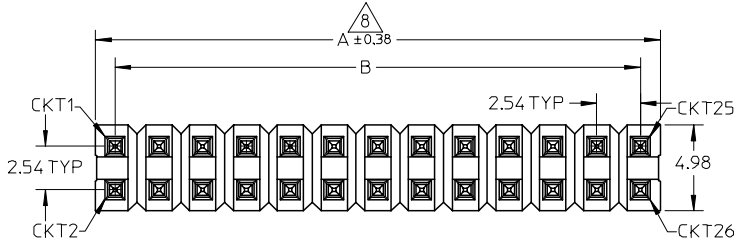
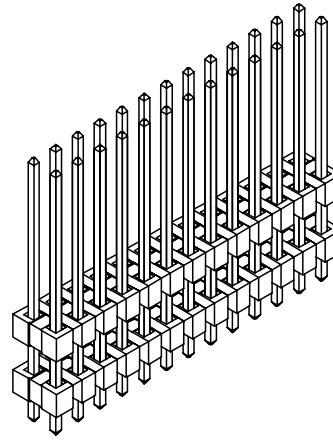


10 9 8 7 6 5 4 3 2 1

PART NO FOR TRAY PACKAGING	CKT SIZE	P E G	VOID PIN POSITION	DIMENSION	
				A	B
87797-0026	26	N	-----	33.02	30.48

NOTES

- MATERIAL:
HSG: LCP, GLASS-FILLED, UL94V-0,
COLOR, BLACK
PIN: COPPER ALLOY 0.64 mm SQ.
 - PLATING TYPE:
0.254µm/10µm MIN GOLD IN CONTACT AREA OVER
1.900µm/75µm MIN TIN SELECTIVE IN SOLDER AREA BOTH OVER
1.270µm/50µm NICKEL OVERALL
 - PARTS TO BE PACKED IN TRAY
 - PCB THICKNESS 1.6+/-0.10mm
 - PRODUCT SPECIFICATION: PS-87920-019
 - WAFER TO BE FLAT WITHIN 0.003 mm/m
 - PART IS NOT STACKABLE ON 2.54 CENTER
- △ IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE



EC NO: S2006-1078 DRWN:SKLIM01 CHKD:CWLM APPR:PATEY 2006/05/03	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 3 °	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAWN BY	DATE	TITLE	CUSTOM HEADER 2.54MM PITCH DUAL ROW HEADER,THRU HOLE,26CKT	
	REV	SKLIM01	2006/04/20	MOLEX INCORPORATED	MATERIAL NO. SD-87797-178	
		CWLM	2006/04/28	DOCUMENT NO.	SHEET NO. 1 OF 1	
		PATEY	2006/04/28	SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

9 8 7 6 5 4 3 2 1